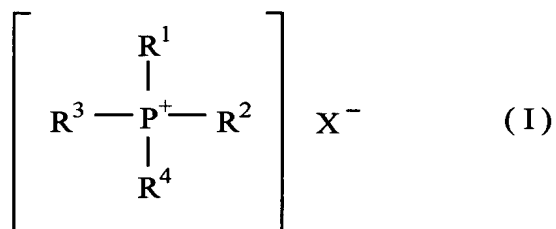
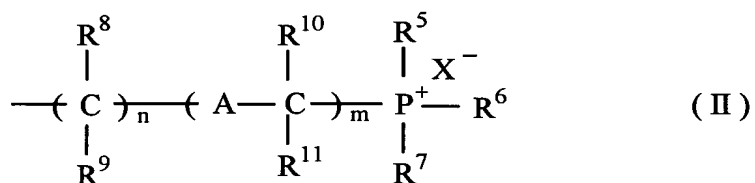


## CLAIMS

1. An epoxy resin composition comprising an epoxy resin, a hardening agent and a hardening accelerator as indispensable ingredients, wherein said hardening accelerator is a phosphonium compound represented by the following formula (I):



- wherein  $\text{R}^1$  to  $\text{R}^4$  are the same or different, and are an optionally substituted alkyl group, an optionally substituted aryl group, an optionally substituted aralkyl group, an optionally substituted diarylmethyl group or a group represented by the following formula (II):



- wherein  $\text{R}^5$  to  $\text{R}^7$  are the same or different, and are an optionally substituted alkyl group, an optionally substituted aryl group, an optionally substituted aralkyl group or an optionally substituted diarylmethyl group,  $\text{R}^8$  to  $\text{R}^{11}$  are the same or different, and are a hydrogen atom,

an optionally substituted alkyl group or an optionally substituted aryl group,

A is an optionally substituted aromatic hydrocarbon ring,

n is an integer of 1 to 5, m is 0 or 1, and

5 X represents a halogen atom, and  $\text{SbF}_6$ ,  $\text{AsF}_6$ ,  $\text{PF}_6$ ,  $\text{BF}_4$  or  $\text{BPh}_4$ ;

provided that at least one of  $\text{R}^1$  to  $\text{R}^4$  is a group represented by the formula (II),

10 or any one of  $\text{R}^1$  to  $\text{R}^4$  and any one of  $\text{R}^5$ - $\text{R}^7$  may be combined together to form a lower alkylene group which forms a heterocyclic ring containing two phosphorus atoms, and X is as defined in the formula (II).

2. The epoxy resin composition according to claim 1 wherein the phosphonium compound is one or more kinds of  
15 phosphonium compound selected from the group consisting of (a) a phosphonium compound wherein, in the above formula (I), at least one of  $\text{R}^1$  to  $\text{R}^4$  is a group represented by the formula (II),  $\text{R}^5$  to  $\text{R}^7$  are the same or different, and are a phenyl group, an optionally substituted benzyl group, a  
20 naphthylmethyl group, an optionally substituted diphenylmethyl group or an optionally substituted alkyl group,  $\text{R}^8$  is a hydrogen atom,  $\text{R}^9$  is a hydrogen atom or a phenyl group, n is an integer of 1 to 4, m is 0, and the rest of  $\text{R}^1$  to  $\text{R}^4$  is a phenyl group, an optionally  
25 substituted benzyl group, a naphthylmethyl group, an

optionally substituted diphenylmethyl group or an optionally substituted alkyl group,

(b) a phosphonium compound wherein, in the above formula (I),  $R^2$  is a group represented by the formula (II),  $R^6$ ,  $R^7$  and  $R^9$  are a phenyl group,  $R^8$  is a hydrogen atom,  $m$  is 0,  $n$  is 2,  $R^1$  and  $R^5$  are combined together to form a  $C_{1-4}$  alkylene group, and  $R^3$  and  $R^4$  are a phenyl group,

(c) a phosphonium compound wherein, in the above formula (I),  $R^1$  is a group represented by the formula (II),  $R^5$  to  $R^7$  are a phenyl group or a group represented by the formula:  $-(CH_2)_p-PPh_2$  (wherein,  $p$  is an integer of 1 to 4),  $R^8$  to  $R^{11}$  are a hydrogen atom,  $A$  is an optionally substituted benzene ring,  $m$  and  $n$  are 1, and  $R^2$  to  $R^4$  are a phenyl group or a group represented by the formula:  $-(CH_2)_p-PPh_2$  (wherein,  $p$  is an integer of 1 to 4),

(d) a phosphonium compound wherein, in the above formula (I),  $R^2$  is a group represented by the formula (II),  $R^6$  and  $R^7$  are a phenyl group,  $R^8$  to  $R^{11}$  are a hydrogen atom,  $A$  is an optionally substituted benzene ring,  $m$  and  $n$  are 1,  $R^1$  and  $R^5$  are combined together to form a  $C_{1-8}$  alkylene group, and  $R^3$  and  $R^4$  are a phenyl group.

3. The epoxy resin composition according to claim 1, wherein the amount of a phosphonium compound to be added is 0.05 to 5 parts by weight (phr) relative to 100 parts by weight (phr) of epoxy resin.

4. The epoxy resin composition according to claim 1, wherein the epoxy resin comprises a triazine derivative epoxy resin.

5. A hardened resin which is obtained by heating  
5 and curing the epoxy resin composition according to claim 1.